3.5 x2.8mm SMD CHIP LED LAMP

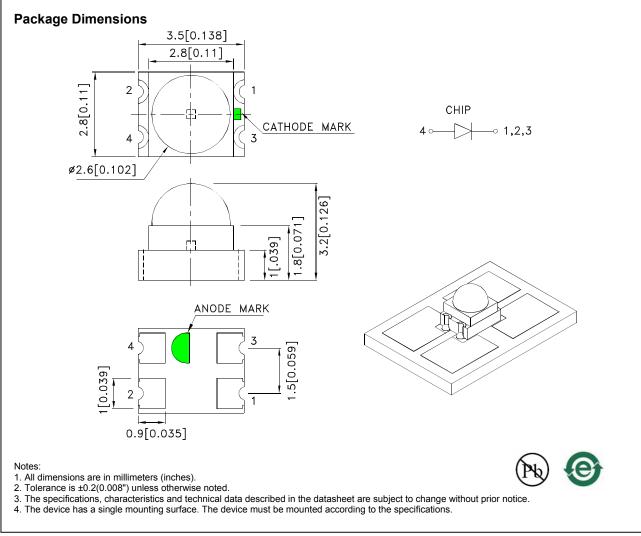
Part Number: APETD3528SEC/J3-PRV Hyper Red

Features

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red device is based on light emitting diode chip made from AlGaInP.



REV NO: V.3 CHECKED: Allen Liu DATE: MAY/18/2011 DRAWN: J.Yu

PAGE: 1 OF 5 ERP: 1203009658

Selection Guide

Selection Guide							
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		· /···		Viewing Angle [1]
			Min.	Тур.	201/2		
APETD3528SEC/J3-PRV	Hyper Red (AlGaInP)	Water Clear	3500	4200	60°		

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	640		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	625		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	25		nm	I⊧=20mA
С	Capacitance	Hyper Red	27		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	2.2	2.8	V	IF=20mA
lr	Reverse Current	Hyper Red		10	uA	Vr=5V

Notes:

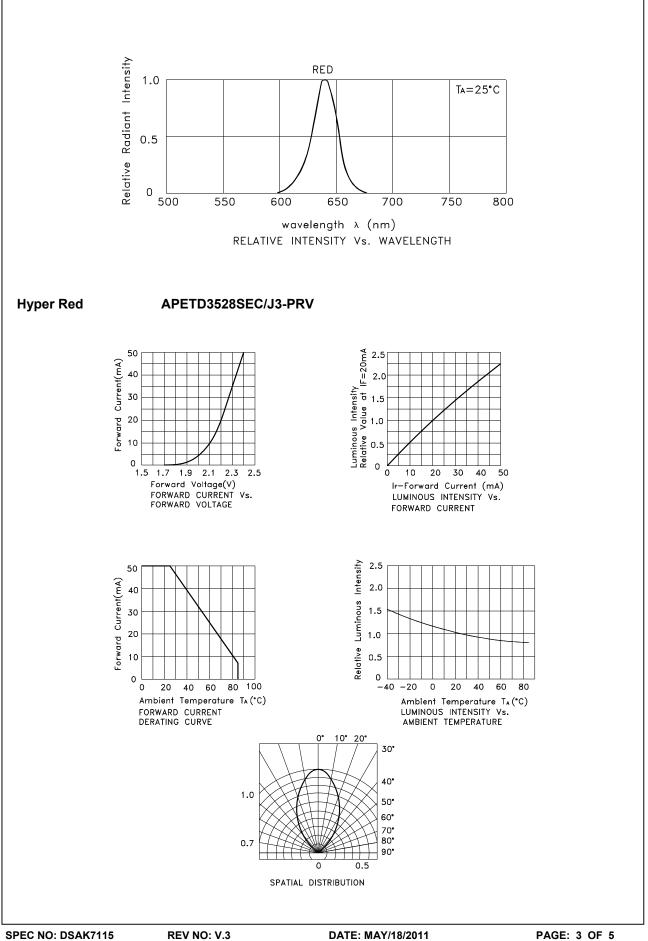
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red			
Power dissipation	140	mW		
DC Forward Current	50	mA		
Peak Forward Current [1]	150	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note:

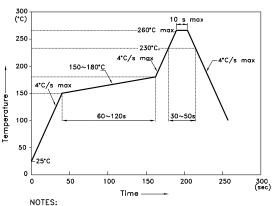
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



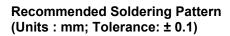
APETD3528SEC/J3-PRV

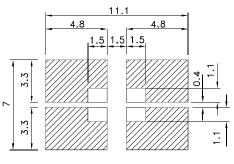
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



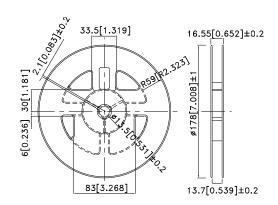
NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.



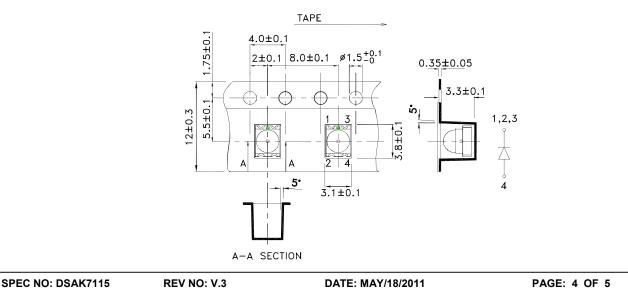


🛛 Solder resist

Reel Dimension



Tape Dimensions (Units : mm)



APPROVED: WYNEC

CHECKED: Allen Liu

DRAWN: J.Yu

ERP: 1203009658

